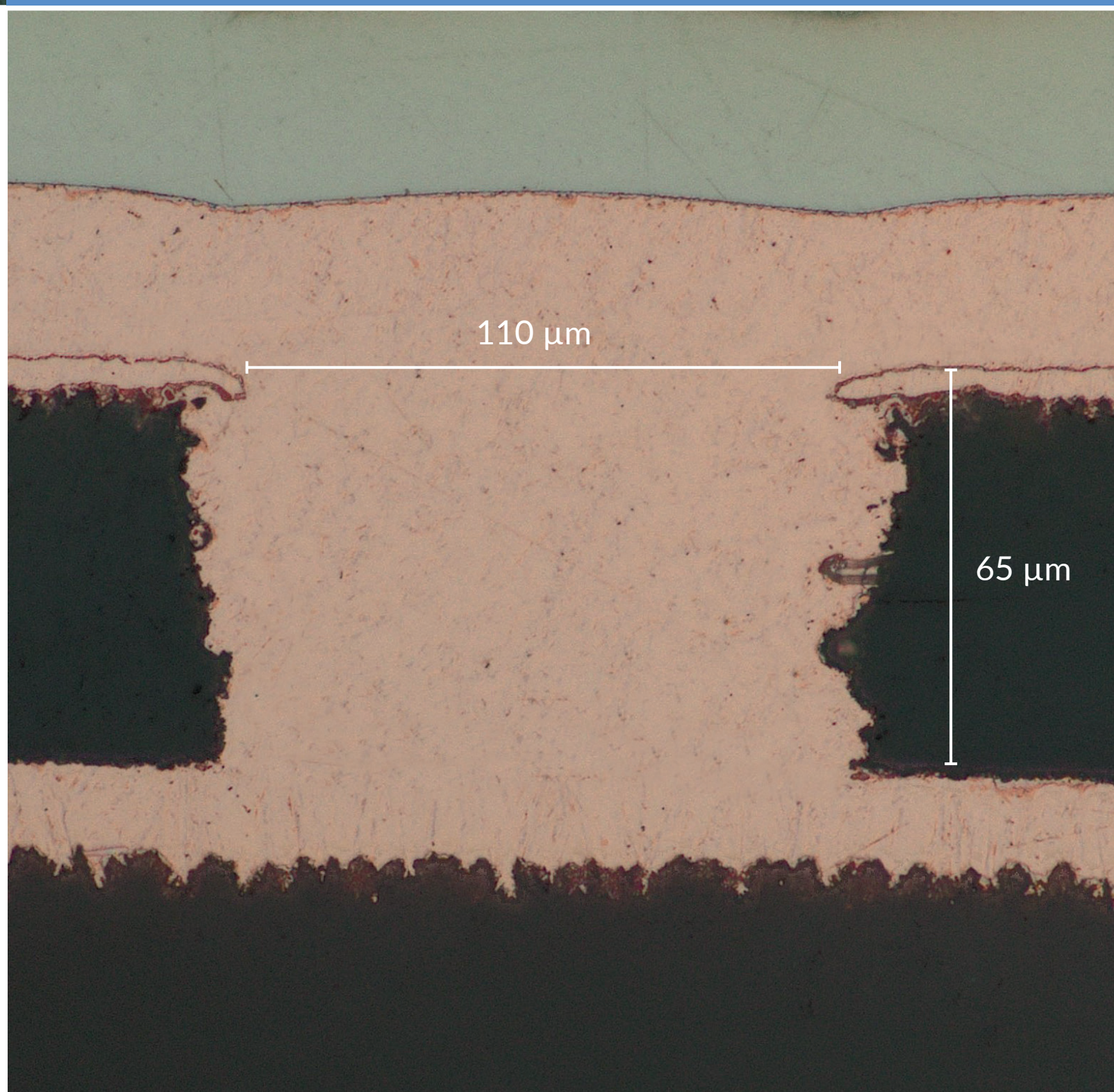


(a)mSAP BMV filling for best uniformity with high ductility

High current density (3.0 A/dm²)
BMV filling

Excellent crystal structure even
at high current density



Up to

3.0

A/dm² applicable
current density

25%

ductility

Excellent ductility

InPro[®] THF2 is a through hole and BMV filling process for use in VCP systems with insoluble anodes. The next generation process allows for highest ductility at high applicable current densities especially for amSAP production where increased flexibility of substrates is required. The excellent filling performance is adjustable over a wide working window to ensure reliable manufacturing on various substrate designs.

Features and benefits

- High applicable current densities: up to 3.0 A/dm² for pattern BMV filling
- High ductility for best amSAP production capability
- Excellent filling performance at high current densities
- Good panel and pattern capability
- For VCP with inert anodes and sparger electrolyte agitation
- Easy control of additives using CVS